



Initial Product/Process Change Notification

Document #: IPCN25156X

Issue Date: 14 Dec 2022

Title of Change:	WDFN6 Assembly Transfer from UTAC to Seremban Malaysia Site 1.	
Proposed First Ship date:	30 Aug 2023 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or BernardRajVellangani.Pelevindran@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >	
Marking of Parts/ Traceability of Change:	Changed material may be identified by lot code or date code	
Change Category:	Assembly Change	
Change Sub-Category(s):	Manufacturing Site Transfer	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Seremban, Malaysia		
Description and Purpose:		
	From	To
Assembly Site	UTAC, Thailand	onsemi Seremban, Malaysia (SBN Site 1)
LeadFrame	SFS Wettable Flank	Step Cut Wettable Flank
Die Attach	1. ABLETHERM 8600 CONDUCTIVE (NSS60100DMTTBG, NSS60101DMTTBG, NSS60200DMTTBG, NSS60200SMTTBG, NSS60201SMTTBG). 2. EPOXY ABLESTICK 8200T (NSS20200DMTTBG, NSS20201DMTTBG)	CRM1084P (All Device)
Bond Wire	1.3mil Gold Wire	1.3mil Palladium Coated Copper Wire
Mold Compound	1. Sumitomo G770HCD (NSS60100DMTTBG, NSS60101DMTTBG, NSS60200DMTTBG, NSS60200SMTTBG, NSS60201SMTTBG). 2. MC G700LTD (NSS20200DMTTBG, NSS20201DMTTBG)	MC EME-G720D Type (All Device)



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Qualification Plan:

QV DEVICE NAME: NSV60101DMTWTBG & NSV60200DMTWTBG

RMS: S86916(NSV60101DMTWTBG) & S74843, S73609(NSV60200DMTWTBG)

PACKAGE: WDFN6 2.0mmx2.0mmx0.75mm

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Tj = Max rate Tj for device, bias = 100% of rated V for Q 101 Rev D	2016 hrs
HTSL	JESD22-A103	Ta =Max rate storage temp for device	2016 hrs
ELFR	AECQ100-008	may utilize either HTGB or HTRB conditions	48 hrs
PC	J-STD-020 JESD-A113	IR reflow at 260C	
HAST + PC	JESD22-A110	130°C, 85% RH, 18.8psig, bias 80% of rated V or 100V max	192 hrs
H3TRB + PC	JESD22-A101	Temp = +85°C; RH = 85%, 80% rated Volt	2016 hrs
TC + PC	JESD22-A104	Temp = -55°C to +150°C	2000 cycle
UHAST + PC	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
IOL+PC	MIL STD750, M 1037 AEC Q101	Ta=+25°C, deltaTj=100°C max, xxx min Ton=Toff (pkg dependent)	2x cycle
RSH	JESD22- B106	Ta=268°C 10 sec dwell	
SD	JSTD002	Ta = 245°C, 5 sec	
Shift	AEC-Q101, MSB17722C	Post 1X HTRB, HTGB, HTSL, TC, HAST/H3TRB, IOL, AC/uHAST	

Estimated date for qualification completion: **10 April 2023**

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NSS60201SMTTBG	NSV60101DMTWTBG
NSS60200SMTTBG	NSV60200DMTWTBG
NSS60200DMTTBG	NSV60200DMTWTBG
NSS60101DMTTBG	NSV60101DMTWTBG
NSS60100DMTTBG	NSV60200DMTWTBG
NSS20201DMTTBG	NSV60101DMTWTBG
NSS20200DMTTBG	NSV60200DMTWTBG